

## 1.6X0.8mm SMD CHIP LED LAMP (0.25mm Height)

Green

Part Number: APG1608ZGC/G



**ATTENTION** OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE

**DEVICES** 

### **Features**

- 1.6mmX0.8mm SMT LED, 0.25mm thickness.
- Low power consumption.
- Wide viewing angle.
- Compatible with automatic placement equipment.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

### Description

The Green source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

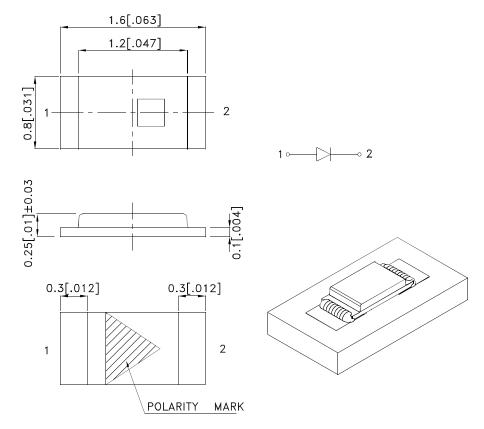
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

## **Applications**

- 1. Mobile phone Keypad indicator and backlight.
- 2.Flat backlight for LCD, switch and symbol.
- 3.Toys.

## **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

4. The device has a single mounting surface. The device must be mounted according to the specifications.



SPEC NO: DSAJ8713 **REV NO: V.2 DATE: DEC/30/2009** PAGE: 1 OF 5 APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Q.Q.Zhu ERP: 1203010214

## **Selection Guide**

| Part No.     | Dice          | Dice Lens Type Iv (mcd) [2] @ 20mA |      | ,    | Viewing<br>Angle [1] |
|--------------|---------------|------------------------------------|------|------|----------------------|
|              |               | 2.                                 | Min. | Тур. | 201/2                |
| APG1608ZGC/G | Green (InGaN) | WATER CLEAR                        | 380  | 700  | 120°                 |

- Notes: 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter                | Device | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|--------|------|------|-------|-----------------|
| λpeak  | Peak Wavelength          | Green  | 520  |      | nm    | IF=20mA         |
| λD [1] | Dominant Wavelength      | Green  | 525  |      | nm    | IF=20mA         |
| Δλ1/2  | Spectral Line Half-width | Green  | 35   |      | nm    | IF=20mA         |
| С      | Capacitance              | Green  | 100  |      | pF    | VF=0V;f=1MHz    |
| VF [2] | Forward Voltage          | Green  | 3.2  | 4    | V     | IF=20mA         |
| lR     | Reverse Current          | Green  |      | 10   | uA    | VR=5V           |

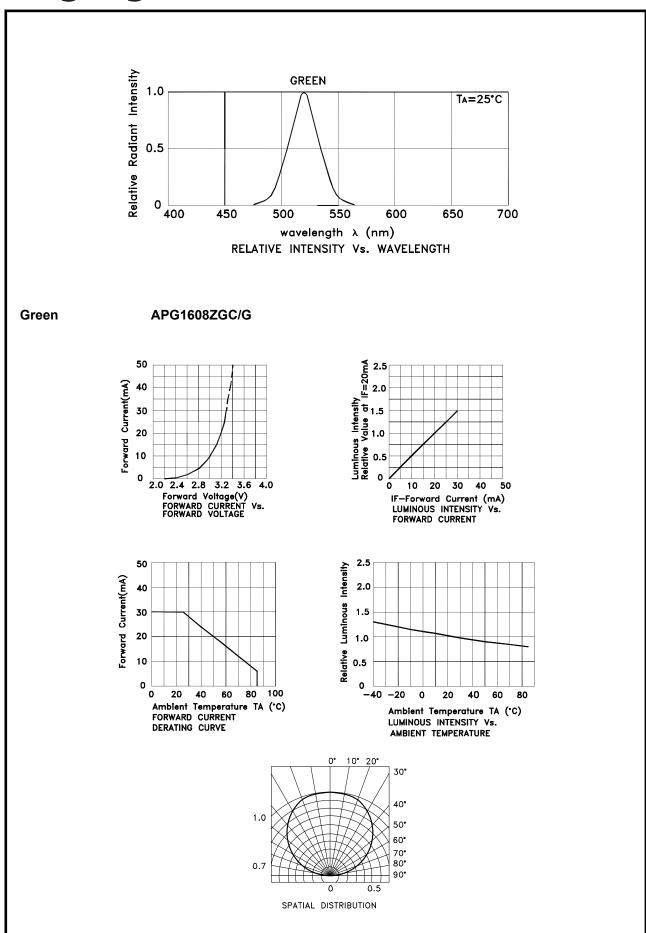
- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

| Green          | Units                                   |  |
|----------------|---|--|
| Green          |   |  |
| 120            | mW                                      |  |
| 30             | mA                                      |  |
| 100            | mA                                      |  |
| 5              | V                                       |  |
| -40°C To +85°C |   |  |
| -40°C To +85°C |   |  |
|                | 120<br>30<br>100<br>5<br>-40°C To +85°C |  |

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

SPEC NO: DSAJ8713 **REV NO: V.2** DATE: DEC/30/2009 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Q.Q.Zhu ERP: 1203010214



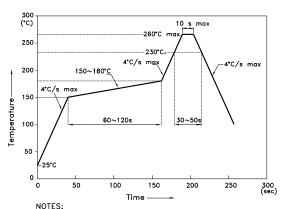
 SPEC NO: DSAJ8713
 REV NO: V.2
 DATE: DEC/30/2009
 PAGE: 3 OF 5

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Q.Q.Zhu
 ERP: 1203010214

### APG1608ZGC/G

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



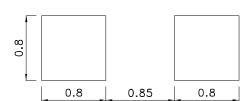
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

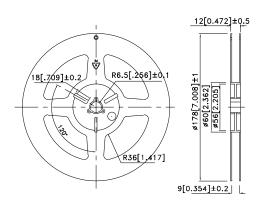
  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
  - to high temperature.

    3.Number of reflow process shall be 2 times or less.

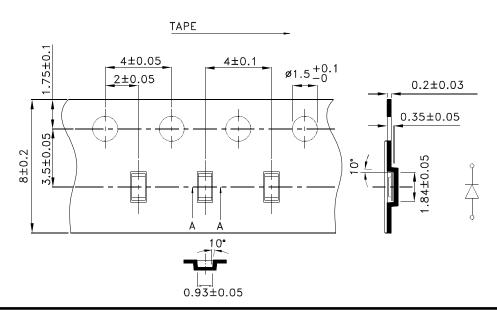
## Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



## **Reel Dimension**

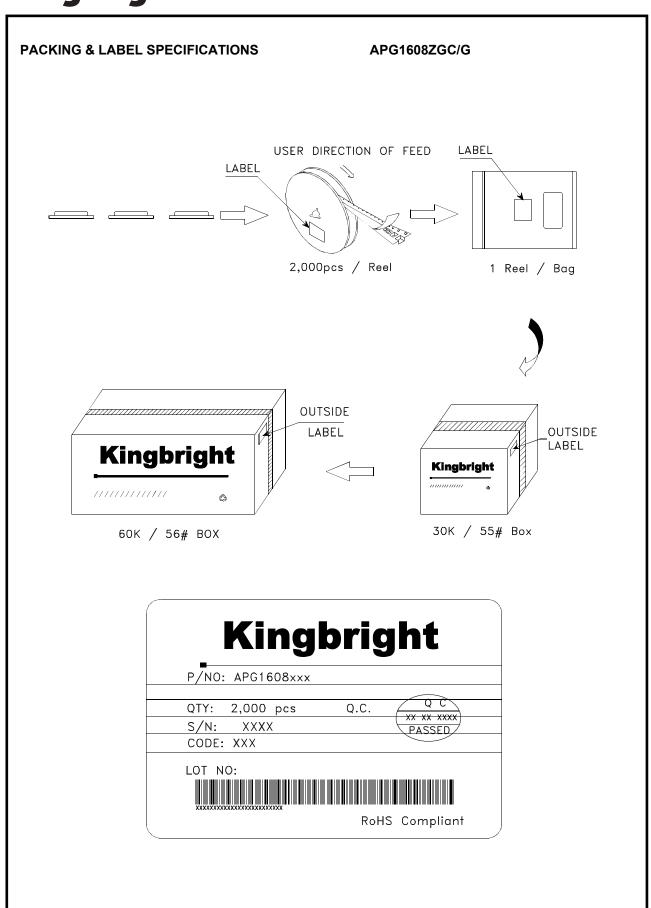


Tape Dimensions (Units : mm)



SPEC NO: DSAJ8713 REV NO: V.2 DATE: DEC/30/2009 PAGE: 4 OF 5

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Q.Q.Zhu ERP: 1203010214



SPEC NO: DSAJ8713 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: DEC/30/2009 DRAWN: Q.Q.Zhu PAGE: 5 OF 5 ERP: 1203010214